12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20240502001.1
Qualification of RFAB as an additional Fab site and Die Revision option for select devices
Change Notification / Sample Request

Date: May 02, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240502001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
DRV5055Z1QDBZR	NULL
DRV5055Z2QDBZR	NULL
DRV5055Z3QDBZR	NULL
DRV5055Z4QDBZR	NULL
DRV5056A1QDBZR	NULL
DRV5056A2QDBZR	NULL
DRV5056A3QDBZR	NULL
DRV5056A4QDBZR	NULL
DRV5056A6QDBZR	NULL
DRV5056Z1QDBZR	NULL
DRV5056Z2QDBZR	NULL
DRV5056Z3QDBZR	NULL
DRV5056Z4QDBZR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240502001.1	PCN Date:	May 02, 2024
Title:	Qualification of RFAB as an additional Fab site and Die Revision option for select devices		
Customer Contact:	Change Management Team	Dept:	Quality Services
Proposed 1st Ship Date:	July 31, 2024	Sample requests accepted until:	June 01, 2024*

*Sample requests received after June 01, 2024 will not be supported.

Change Type:

☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☒	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☒	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☒	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its RFAB fabrication facility as an additional Wafer Fab option for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	**Process**	**Wafer Diameter**	**Additional Fab site**	**Process**	**Wafer Diameter**
MIHO8	LBC8	200mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

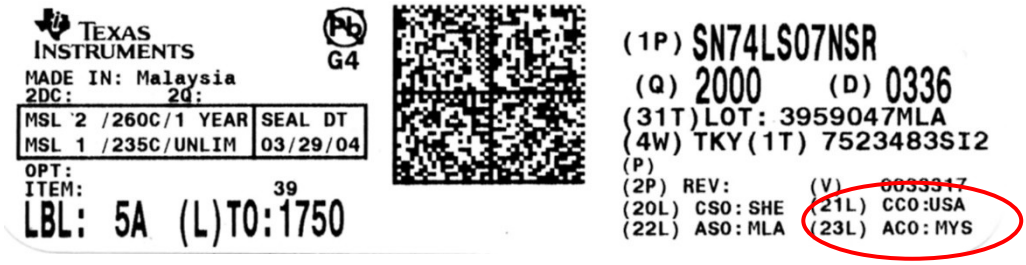
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
RFAB	**RFB**	**USA**	**Richardson**

Die Rev:

Current	New
Die Rev [2P]	**Die Rev [2P]**
A	**C**

Sample product shipping label (not actual product label):



Product Affected:

DRV5055Z1QDBZR	DRV5056A1QDBZR	DRV5056A6QDBZR	DRV5056Z4QDBZR
DRV5055Z2QDBZR	DRV5056A2QDBZR	DRV5056Z1QDBZR	
DRV5055Z3QDBZR	DRV5056A3QDBZR	DRV5056Z2QDBZR	
DRV5055Z4QDBZR	DRV5056A4QDBZR	DRV5056Z3QDBZR	

Qualification Report

Approve Date 18-December-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	**Qual Device: DRV5055A2QDBZR**	Qual Device: DRV5055A3QDBZR	**Qual Device: DRV5055A4QDBZR**	QBS Reference: TLV62568DBVR	**QBS Reference: TLV62569DBVR**	QBS Reference: DRV5013ADEDBZRQ1	**QBS Reference: DRV5013ADQDBZRQ1**	QBS Reference: TL431BQDBZRQ1	QBS Reference: PTMAG5253BA3IQDBZR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	3/231/0	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	3/231/0	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0	3/231/0	3/231/0	-
TC	A4	Temperature Cycle	-55C/150C	1000 Cycles	-	-	-	-	-	-	-	3/231/0	-	-
TC	A4	Temperature Cycle	-55C/150C	1500 Cycles	-	-	-	-	-	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	-	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	3/231/0	-	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	-	3/135/0	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	2000 Hours	-	-	-	-	-	-	3/135/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	3/231/0	-	-	-	-
HTOL	B1	Life Test	150C	1000 Hours	-	-	-	-	-	-	1/77/0	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0	-	-	1/77/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/3000/0	3/2400/0	-	-	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-

Type	#	Test Name	Condition	Duration	Qual Device: DRV5055A1QDBZR	**Qual Device: DRV5055A2QDBZR**	Qual Device: DRV5055A3QDBZR	**Qual Device: DRV5055A4QDBZR**	QBS Reference: TLV62568DBVR	**QBS Reference: TLV62569DBVR**	QBS Reference: DRV5013ADEDBZRQ1	**QBS Reference: DRV5013ADQDBZRQ1**	QBS Reference: TL431BQDBZRQ1	QBS Reference: PTMAG5253BA3IQDBZR
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	-	1/22/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	3/30/0	3/30/0	3/30/0	-
ESD	E2	ESD CDM	-	1500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
ESD	E2	ESD CDM	-	250 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	-	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	-	1/3/0	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	1/3/0	-	-	3/9/0	1/3/0	1/3/0	-	-
ESD	E2	ESD HBM	-	3500 Volts	-	-	-	-	1/3/0	3/9/0	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	-	-	1/3/0	-	1/6/0	3/9/0	1/6/0	1/6/0	-	-
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	1/30/0	-	1/30/0	3/90/0	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	-	-	2/60/0	3/90/0	3/90/0	-
FTY	E6	Final Test Yield	-	-	1/1/0	1/1/0	-	1/1/0	-	-	-	-	1/1/0	-

QBS: Qual By Similarity
Qual Device DRV5055A1QDBZR is qualified at MSL1 260C
Qual Device DRV5055A2QDBZR is qualified at MSL1 260C
Qual Device DRV5055A3QDBZR is qualified at MSL1 260C
Qual Device DRV5055A4QDBZR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.